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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Jung-Chih HU et al.

Confirmation No.: 5769

Serial No.: 10/070,000

Examiner: Edna Wong

Filed: November 27, 2002

Group Art Unit: 1753

Title: ELECTROPLATING SOLUTION FOR COPPER ELECTROPLATING

REPLY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action mailed October 7, 2003, kindly amend the above-identified application as follows.

Amendments to the **Specification** begins on page 2 of this paper.

Amendments and additions to the **Claims** are reflected in the listing of claims which begins on page 13 of this paper.

Amendments to the **Drawings** begin on page 15 of this paper and include attached replacement sheets.

Remarks/Arguments begin on page 16 of this paper.

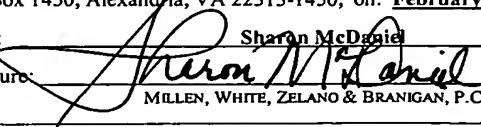
CERTIFICATION OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Services as First Class Mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on: February 9, 2004

Name:

Sharon McDaniel

Signature:


MILLEN, WHITE, ZELANO & BRANIGAN, P.C.